BT150S-600R

SCR

Rev.02 - 19 March 2025 Product data sheet

1. General description

Planar passivated SCR with sensitive gate in a TO252 (DPAK) surface mountable plastic package. These devices are intended to be interfaced directly to microcontrollers, logic integrated circuits and other low power gate trigger circuits.

2. Features and benefits

- Sensitive gate
- Planar passivated for voltage ruggedness and reliability
- Direct triggering from low power drivers and logic ICs
- Surface mountable package

3. Applications

- General purpose switching
- Protection Circuits

4. Quick reference data

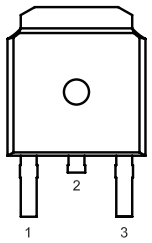
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage		[1]	-	-	600	V
V_{RRM}	repetitive peak reverse voltage			-	-	600	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 111$ °C; Fig. 1		-	-	2.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 111$ °C; Fig. 2; Fig. 3		-	-	4	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig. 4; Fig. 5		-	-	35	A
		half sine wave; $T_{j(init)} = 25$ °C; $t_p = 8.3$ ms		-	-	38	A
T_j	junction temperature		[2]	-	-	125	°C
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12$ V; $I_T = 0.1$ A; $T_j = 25$ °C; Fig. 7		-	15	200	µA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 402$ V; $T_j = 125$ °C; $R_{GK} = 100$ Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform; Fig. 12		-	50	-	V/µs

[1] Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/µs.
[2] Operation above 110˚C may require the use of a gate to cathode resistor of 1kΩ or less.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
BT150S-600R	TO252	BT150S-600R,118	Reel	2500	TO252N	07-Mar-2025
					TO252Q	05-Mar-2025

7. Marking

Table 4. Marking codes

Type number	Marking codes	
	Assembly factory: N	Assembly factory: Q
BT150S-600R	150S6 PJNxxxx xx	150S6 PJQxxxx xx

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8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		[1]	-	600	V
V_{RRM}	repetitive peak reverse voltage			-	600	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 111$ °C; Fig. 1		-	2.5	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 111$ °C; Fig. 2; Fig. 3		-	4	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; Fig. 4; Fig. 5		-	35	A
		half sine wave; $T_{j(init)} = 25$ °C; $t_p = 8.3$ ms		-	38	A
I^2t	I^2t for fusing	$t_p = 10$ ms; SIN		-	6.1	A²s
dI_T/dt	rate of rise of on-state current	$I_G = 50$ mA		-	50	A/µs
I_{GM}	peak gate current			-	2	A
V_{RGM}	peak reverse gate voltage			-	5	V
P_{GM}	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.5	W
T_{stg}	storage temperature			-40	150	°C
T_j	junction temperature		[2]	-	125	°C

[1] Although not recommended, off-state voltages up to 800V may be applied without damage, but the thyristor may switch to the on-state. The rate of rise of current should not exceed 15 A/µs.

[2] Operation above 110˚C may require the use of a gate to cathode resistor of 1kΩ or less.

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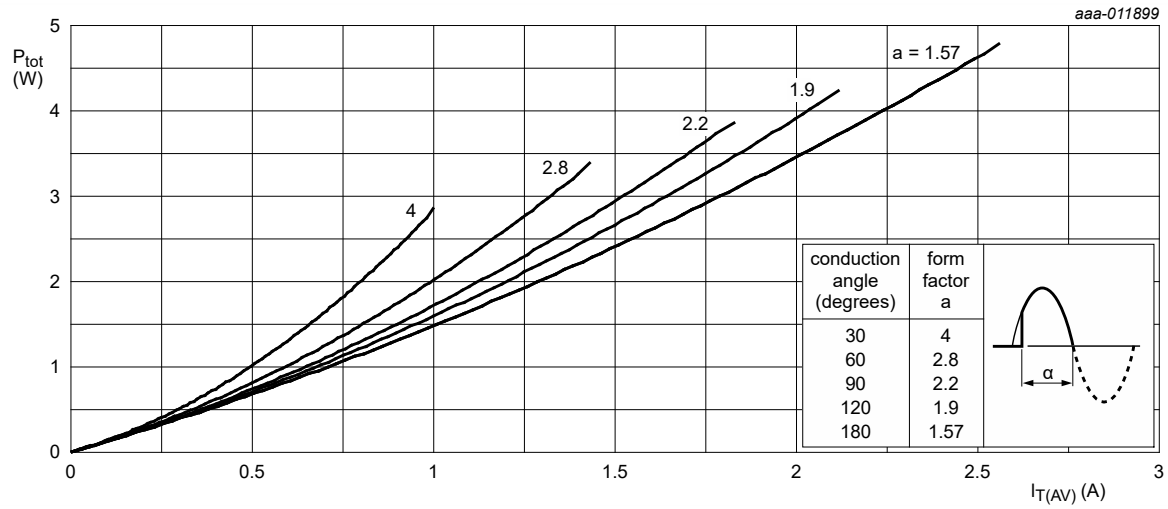


α = conduction angle

a = form factor = $I_{T(RMS)}$ / $I_{T(AV)}$

Fig. 1. Total power dissipation as a function of average on-state current; maximum values

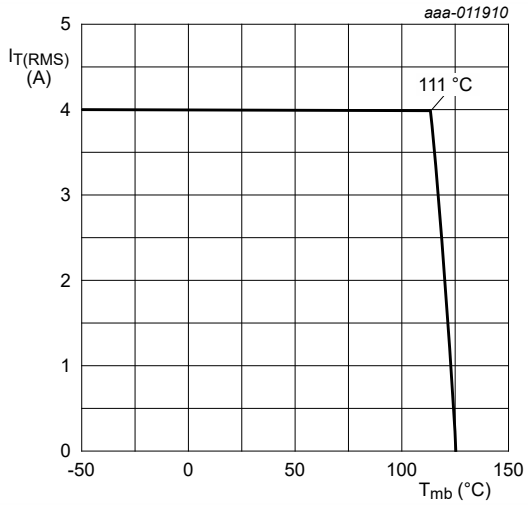
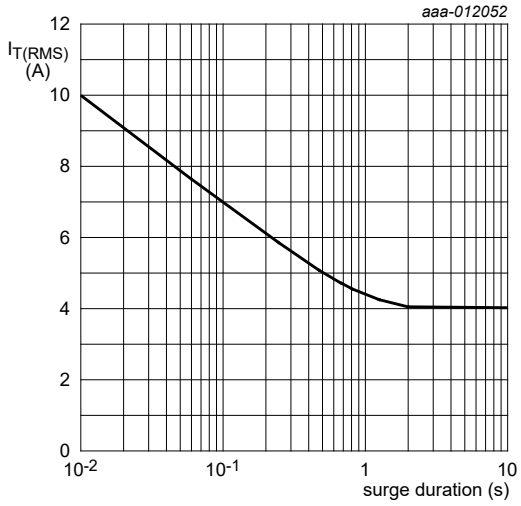


Fig. 2. RMS on-state current as a function of mounting base temperature; maximum values



f = 50 Hz; T_{mb} = 111 °C

Fig. 3. RMS on-state current as a function of surge duration; maximum values

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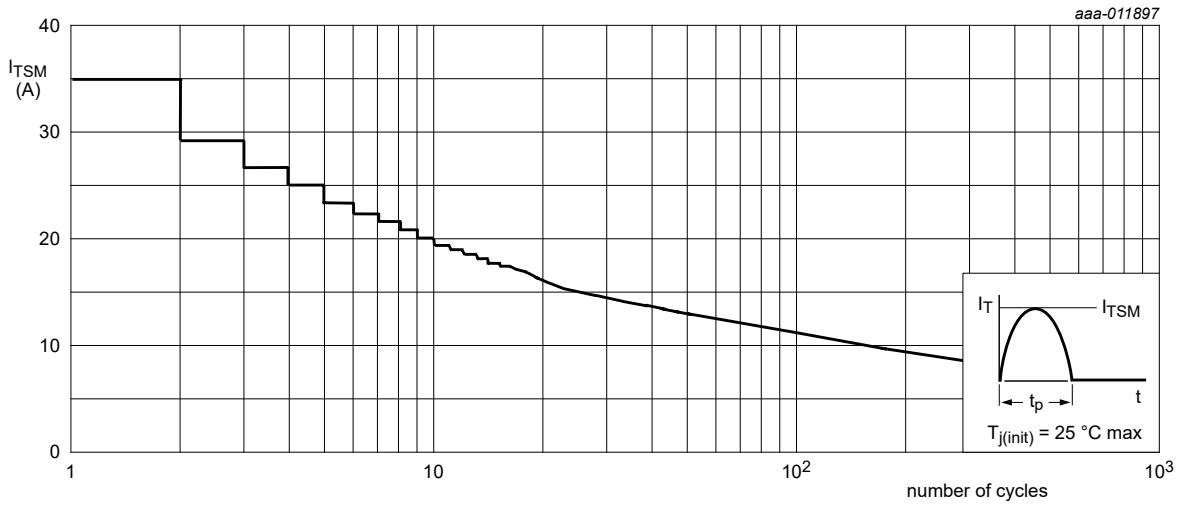
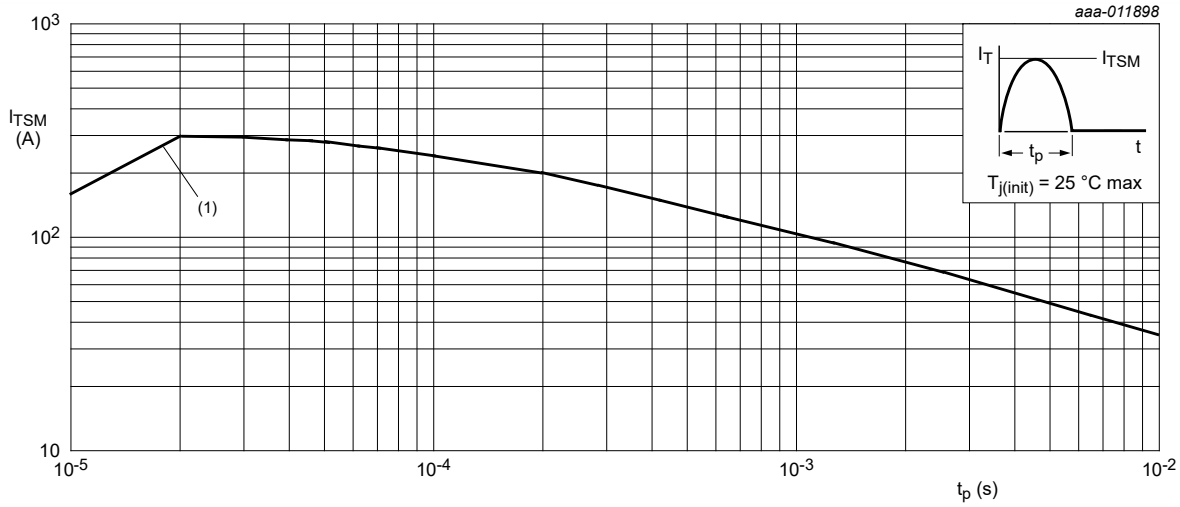


f = 50 Hz

Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



$t_p \leq 10$ ms
(1) dI_T/dt limit

Fig. 5. Non-repetitive peak on-state current as a function of pulse width for sinusoidal currents; maximum values

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9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j\text{-}mb)}$	thermal resistance from junction to mounting base	Fig. 6		-	-	3	K/W
$R_{th(j\text{-}a)}$	thermal resistance from junction to ambient free air	Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint		-	75	-	K/W

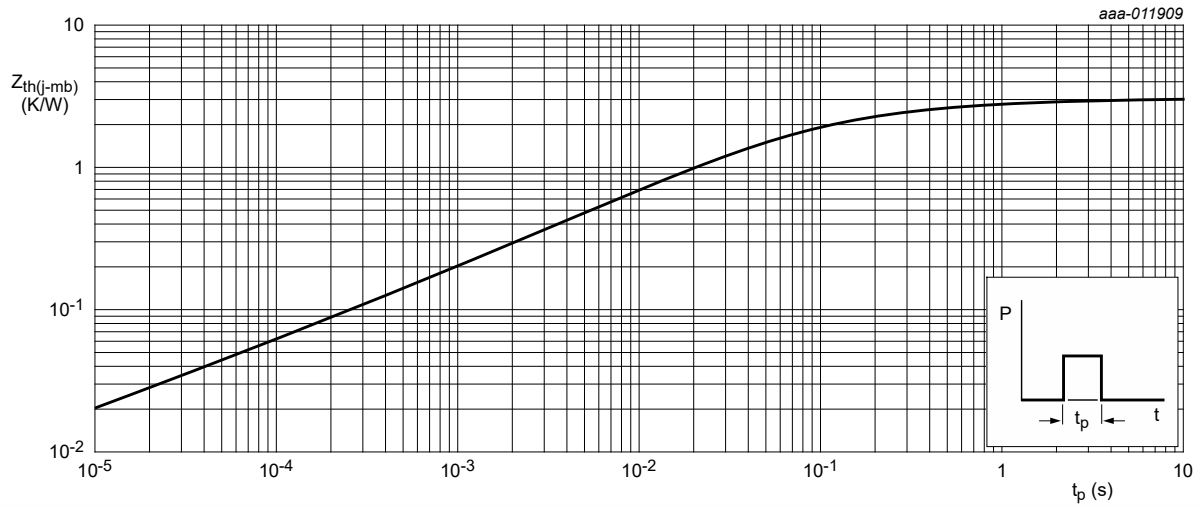

Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

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10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 7		-	15	200	µA
I_L	latching current	V_D = 12 V; I_G = 0.1 A; T_j = 25 °C; Fig. 8		-	0.17	10	mA
I_H	holding current	V_D = 12 V; T_j = 25 °C; Fig. 9		-	0.1	6	mA
V_T	on-state voltage	I_T = 5 A; T_j = 25 °C; Fig. 10		-	1.23	1.8	V
V_{GT}	gate trigger voltage	V_D = 12 V; I_T = 0.1 A; T_j = 25 °C; Fig. 11		-	0.4	1	V
		V_D = 600 V; I_T = 0.1 A; T_j = 110 °C; Fig. 11		0.1	0.2	-	V
I_D	off-state current	V_D = 600 V; T_j = 125 °C		-	0.1	0.5	mA
I_R	reverse current	V_R = 600 V; T_j = 125 °C		-	0.1	0.5	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	V_{DM} = 402 V; T_j = 125 °C; R_{GK} = 100 Ω; (V_{DM} = 67% of V_{DRM}); exponential waveform; Fig. 12		-	50	-	V/µs
t_{gt}	gate-controlled turn-on time	I_{TM} = 10 A; V_D = 600 V; I_G = 5 mA; dI_G/dt = 0.2 A/µs; T_j = 25 °C		-	2	-	µs
t_q	commutated turn-off time	V_{DM} = 402 V; T_j = 125 °C; I_{TM} = 8 A; V_R = 10 V; $(dI_T/dt)_M$ = 10 A/µs; dV_D/dt = 2 V/µs; $R_{GK(ext)}$ = 1 kΩ; (V_{DM} = 67% of V_{DRM})		-	100	-	µs

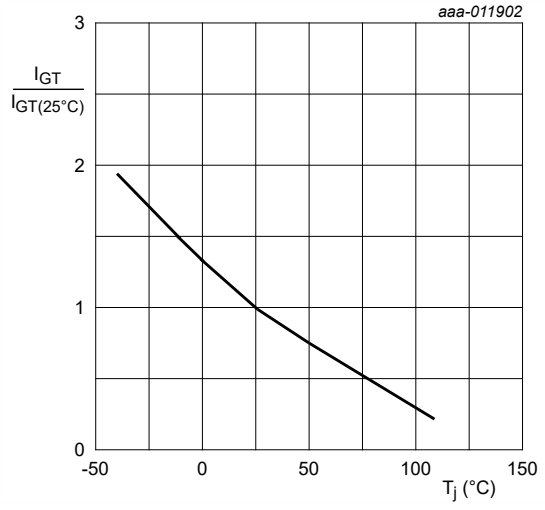
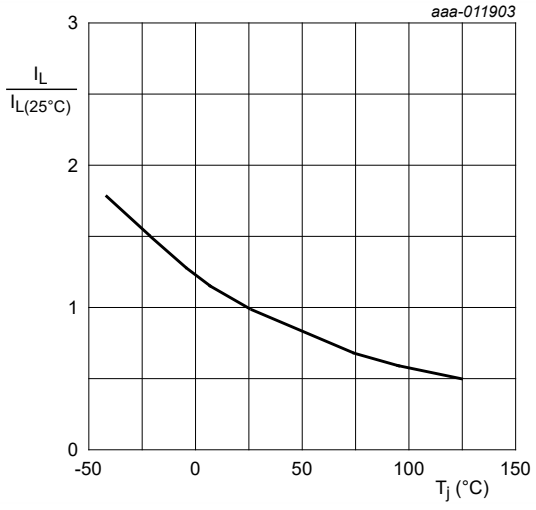


Fig. 7. Normalized gate trigger current as a function of junction temperature



R_{GK} = 1 kΩ

Fig. 8. Normalized latching current as a function of junction temperature

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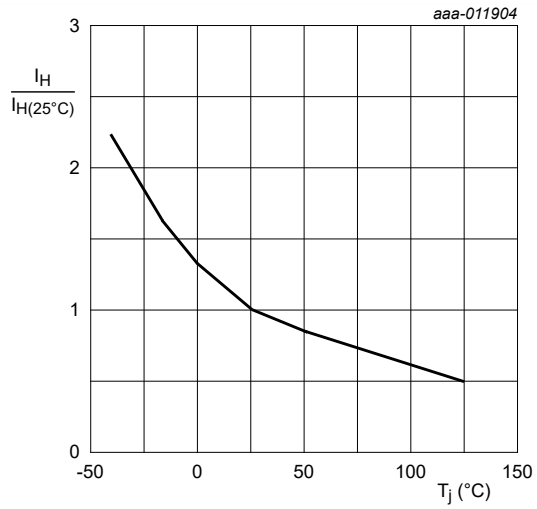
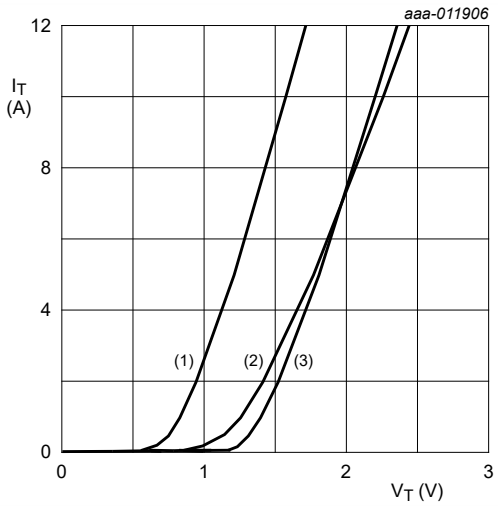


R_{GK} = 1 kΩ

Fig. 9. Normalized holding current as a function of junction temperature



V_o = 1.26 V; R_s = 0.099 Ω
(1) T_j = 125 °C; typical values
(2) T_j = 125 °C; maximum values
(3) T_j = 25 °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

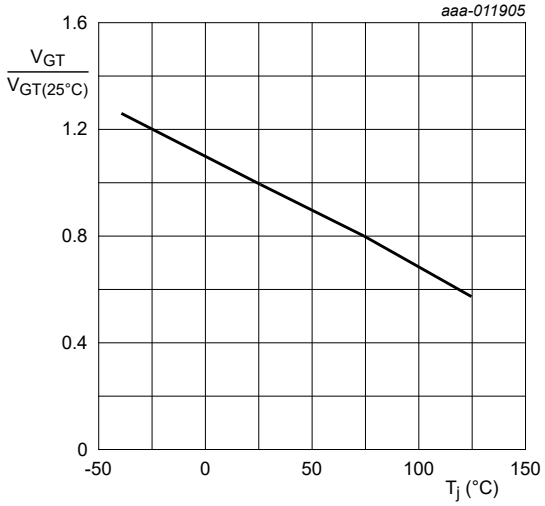
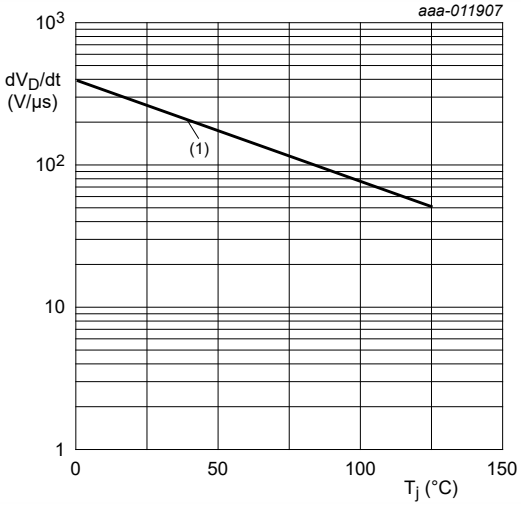


Fig. 11. Normalized gate trigger voltage as a function of junction temperature



(1) R_{GK} = 100 Ω

Fig. 12. Critical rate of rise of off-state voltage as a function of junction temperature; typical values

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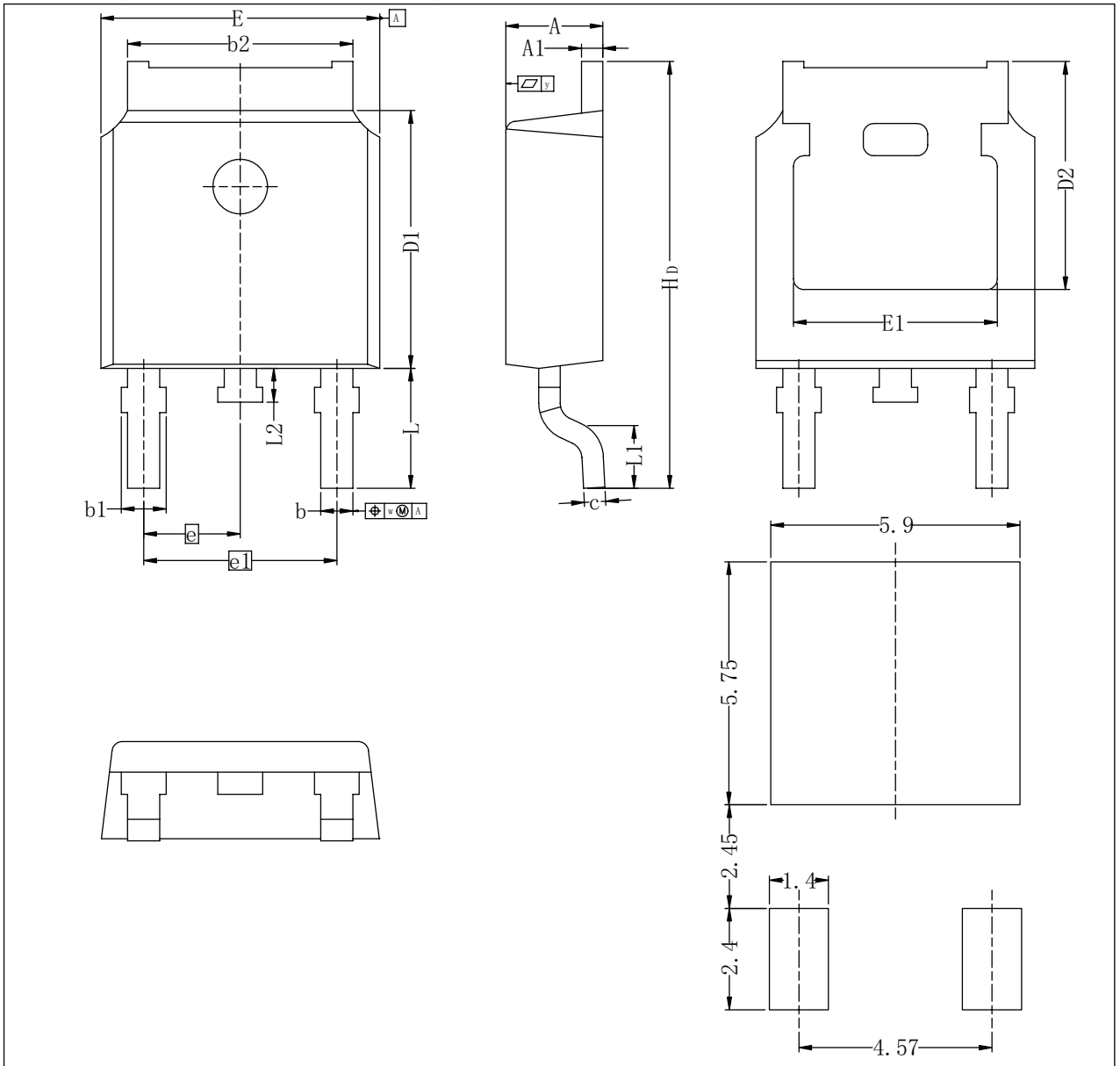
10. Package outline

Assembly factory: N

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped)



Recommended Footprint

Unit	A	A1	b	b1	b2	c	D1	D2	E	E1	e	e1	H_D	L	L1	L2	w	y
min	2.22	0.46	0.71	0.72	5.00	0.20	5.98	4.00	6.47	4.45	2.285	4.57	9.60	2.90 (Ref.)	0.50	0.50	0.20	
mm nom																		
max	2.38	0.93	0.89	1.10	5.46	0.56	6.22	---	6.73	---			10.40		---	0.90		0.20

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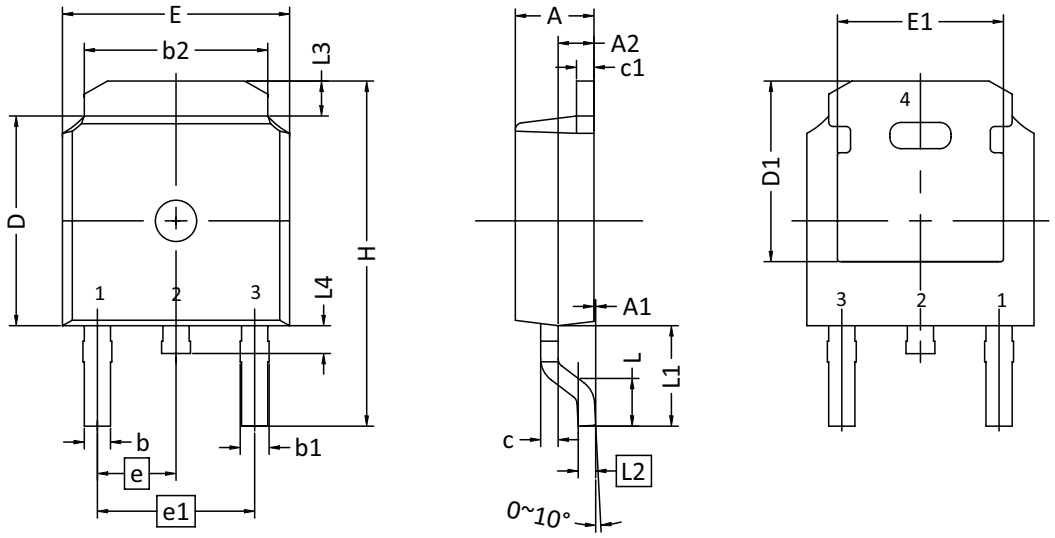
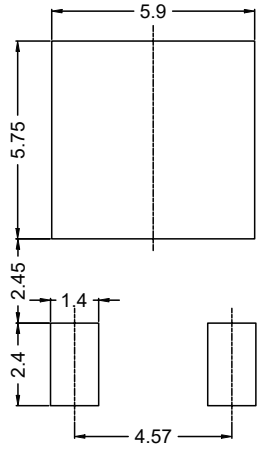
Assembly factory: Q

Plastic single-ended surface-mounted package (DPAK); 3 leads (one lead cropped) TO252





Recommended Footprint

SYMBOLS	DIMENSION IN MM		
	MIN	NOM	MAX
A	2.184	2.286	2.400
A1	0.000	---	0.200
A2	0.889	1.041	1.170
b	0.635	0.762	0.889
b1	0.680	0.840	1.143
b2	4.953	5.340	5.500
c	0.450	0.508	0.610
c1	0.450	0.508	0.630
D	5.969	6.096	6.223
D1	5.210	5.249	5.380
E	6.350	6.604	6.800
E1	4.318	4.826	4.920
e	2.286BSC		
e1	4.572BSC		
H	9.398	10.033	10.500
L	1.270	1.520	2.032
L1	2.921REF		
L2	0.408	0.508	0.608
L3	0.889	1.016	1.270
L4	0.600	---	1.016

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Document status [1][2]	Product status [3]	Definition
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